



# WF100DP

## 1. KEY FEATURES:

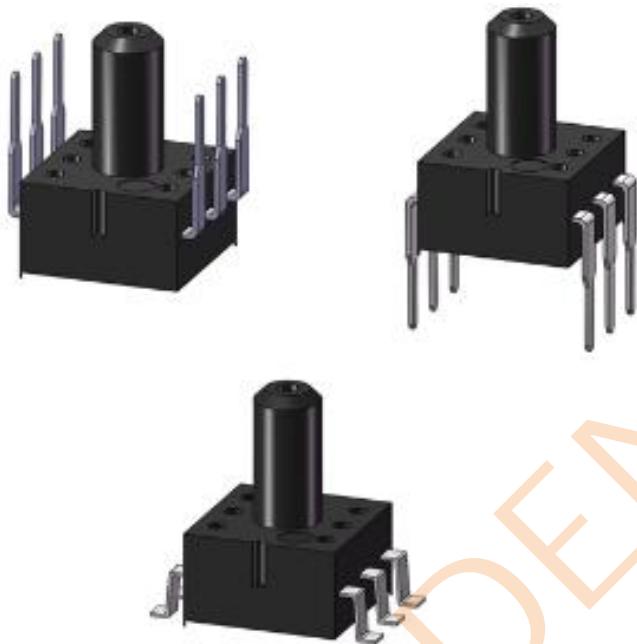
- Piezo-resistive silicon micro-machined sensor
- Gauge type pressure sensor
- I2C / SPI Interface
- Pressure range: 100KPa (5KPa/10KPa/20KPa/40KPa/100KPa/200KPa/300KPa/500KPa/1000KPa)
- Pressure Sensitivity: 0.027 Pa/LSB
- 24 Bit  $\Sigma-\Delta$  ADC
- Temperature Compensation: -40°C ~ 125°C
- Operating voltage 3.0V/(5.0V)
- Operating mode current: ~0.6mA (typical)
- Sleep Mode current: 0.1uA (typical)
- SOP6 or DIP6 package
- RoHS compliant and Halogen-free

## 2. PRODUCT INTRODUCTION:

WF100DP series product is the pressure sensor which measures gauge pressures. It consists of a silicon micro-machined sensing element chip and a signal conditioning ASIC. The ASIC is equipped with a 24-bit resolution  $\Sigma-\Delta$  ADC and outputs a highly precise pressure value as a digital value.

WF100DP series products provides digital output interface. It can achieve ESD robustness, fast response time, high accuracy and linearity as well as long-term stability. All measurement data is fully calibrated and temperature compensated. In addition, it allows for easy system integration.

This series pressure sensor use SOP6 or DIP6 package which is suitable for lots application.



### 3. APPLICATION

- Automobile electronic
- Consumer electronics
- Household electronic
- Industrial monitor and control
- Medicine care

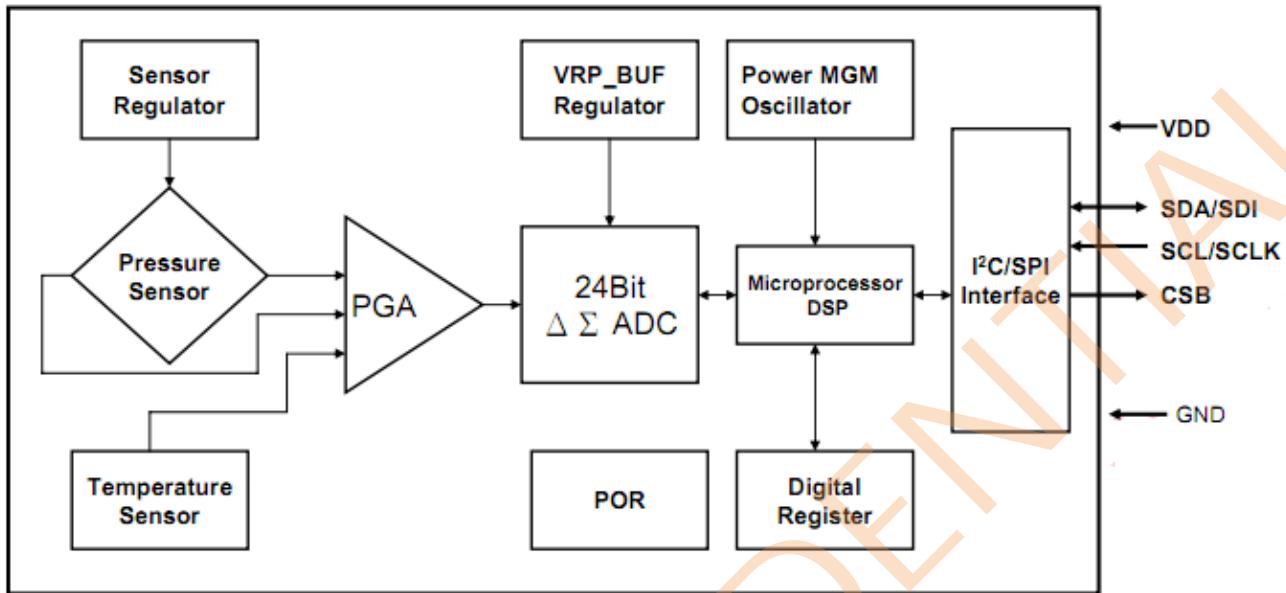


#### 4. PERFORMANCE SPECIFICATIONS

Table 1 Specifications

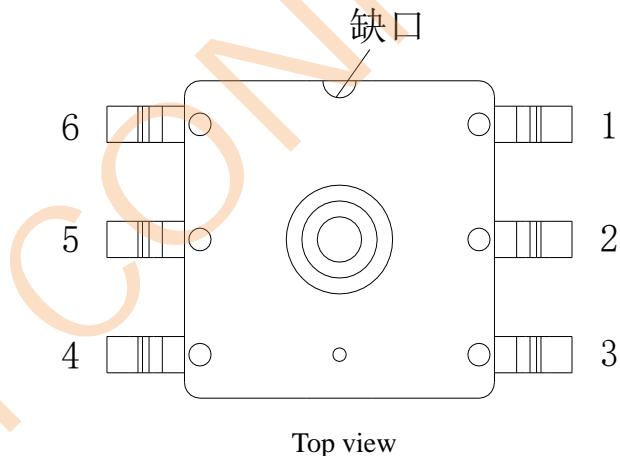
Parameter	Condition	Min.	Typical	Max.	Unit	Remark
Supply Voltage		1.8	3	5.5	Vdc	
Supply Current			1		mAdc	
Pressure range	100 (5/10/20/40/100/200/300/500/1000)				kPa	
Sleep current	25°C	-	0.1	0.3	µA	
Relative accuracy	25°C~40°C	-	±0.3	-	hPa	
Absolute accuracy	-40°C~125°C	-	±4	-	hPa	
Linearity		--	0.2	0.5	%FS	
Resolution of output data in ultra high resolution mode	Pressure	-	0.05	-	Pa	
	Temperature	-	0.01	-	°C	
Absolute accuracy temperature	25°C	-	±0.5	-	°C	
	0°C~65°C	-	±1.0	-	°C	
TCR		1500	2000	2500	ppm/°C	
Stability			0.2		%FS/Y	
Hysteresis		--	0.05	0.1	%FS	
Overpressure			3X		--	
Operation temperature		-40	--	125	°C	
I2C Clock Frequency	3V	-	--	3.4	MHz	
SPI Clock Frequency	3V	-	1	20	MHz	
Tupdae_P	3V	-	2.5	-	ms	
Tupdae_T	3V	-	2.5	-	ms	

## 5. APPLICATION SCHEMATIC



pressure sensor schematic

## 6.CONNECTIONS



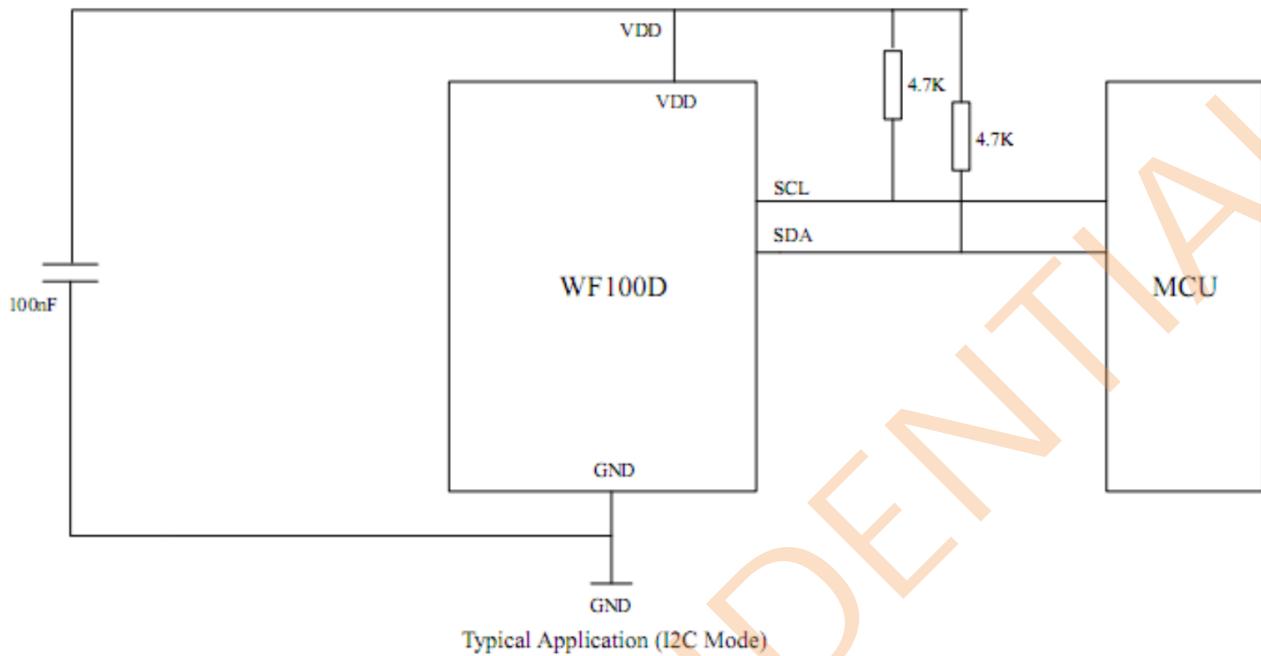
Top view

Table2 Definition

Pin number	Definition	Definition
1	GND	Connected to GND
2	SCL	Clock input for I <sup>2</sup> C/SPI
3	SDA	(1) Data in/out for I <sup>2</sup> C. (2) Data input for SPI.
4	CSB	Pulling Low = SPI, NC = I <sup>2</sup> C
5	VDD	Positive supply voltage
6	NC	NC

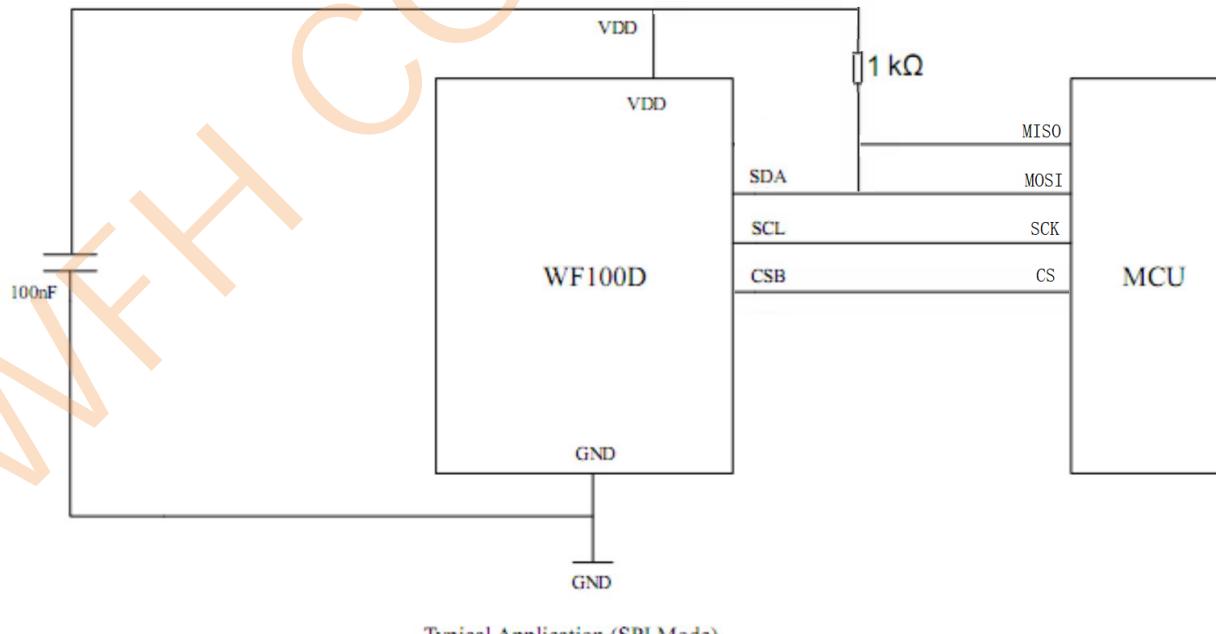
Remark: the connections definition is same for SOP and DIP package product

## 7. CONNECTION DIAGRAM

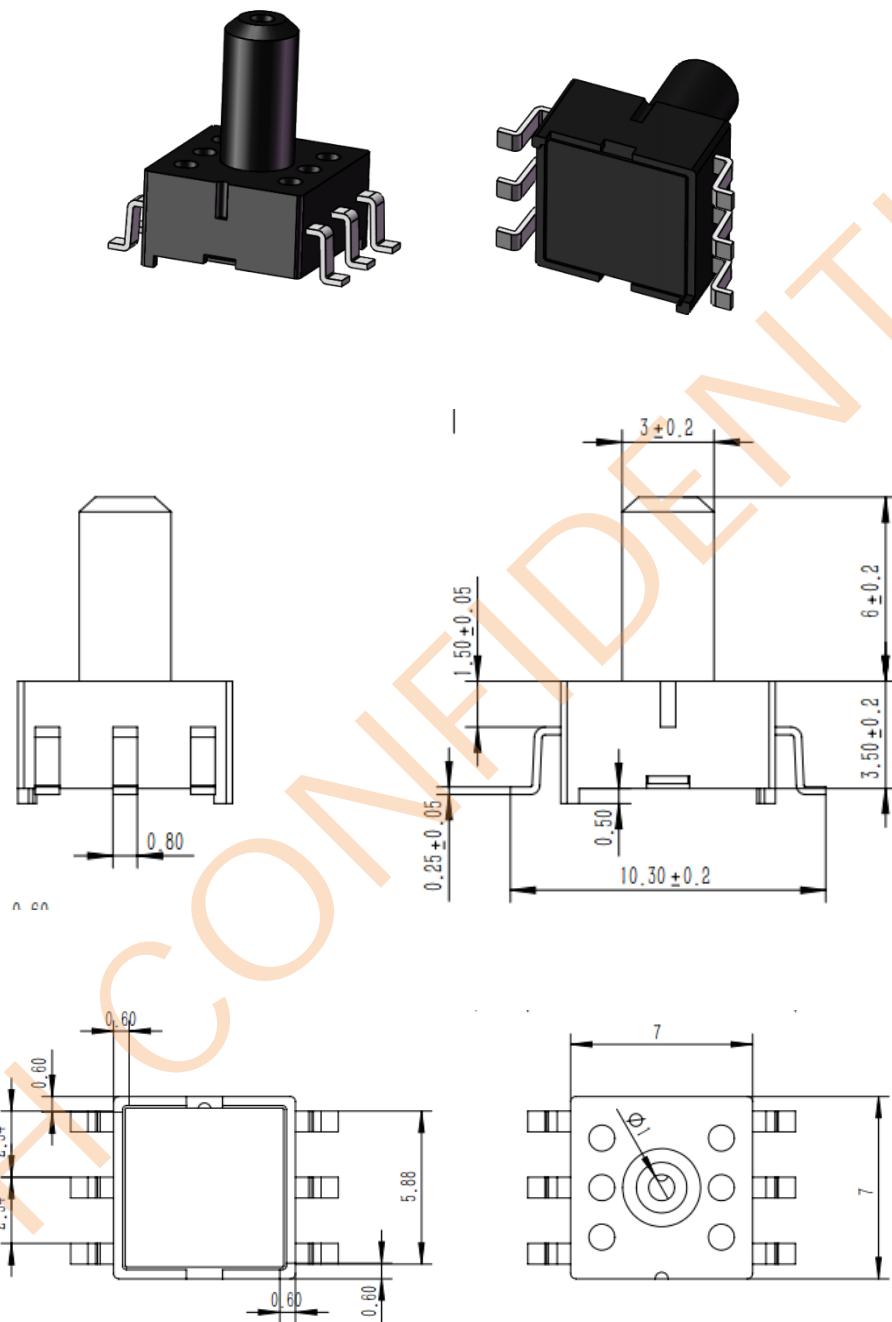


### Notes:

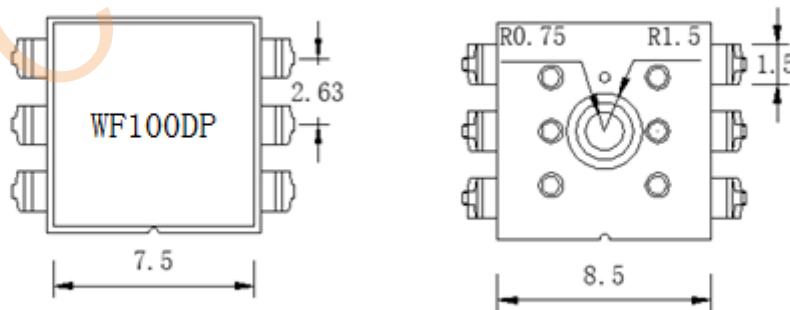
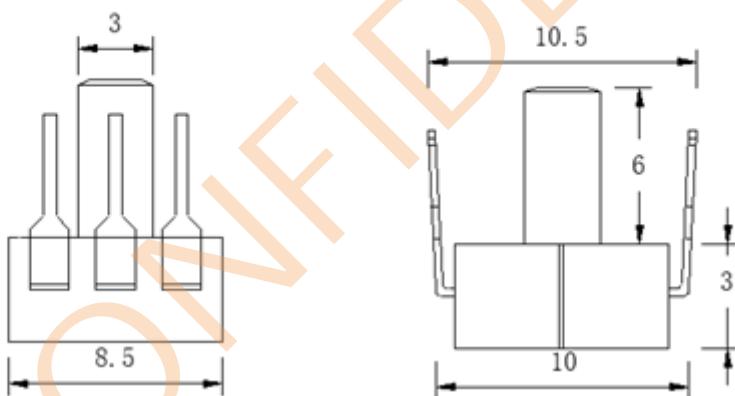
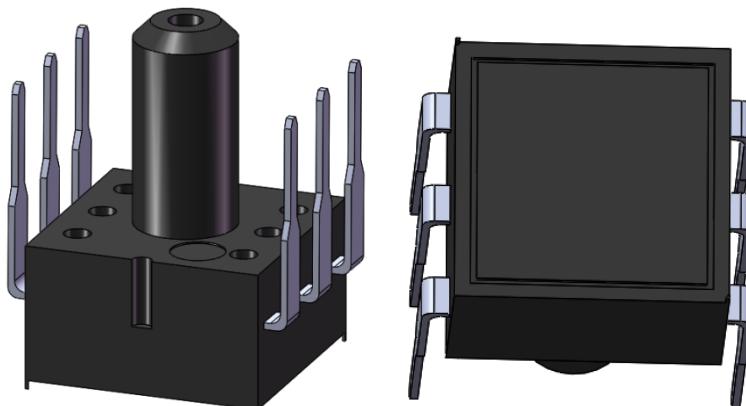
- The recommended value for C<sub>1</sub> is 100nF
- The value for the pull-up resistors R<sub>1</sub>, R<sub>2</sub> should be based on the interface timing and the bus load; a normal value of R<sub>1</sub> is 4.7kΩ, R<sub>2</sub> is 4.7kΩ.



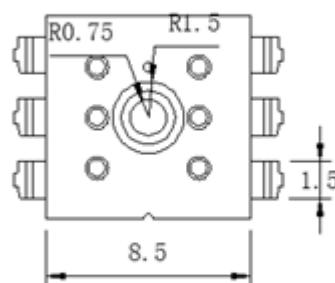
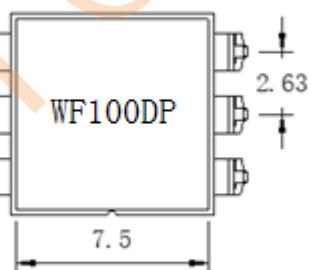
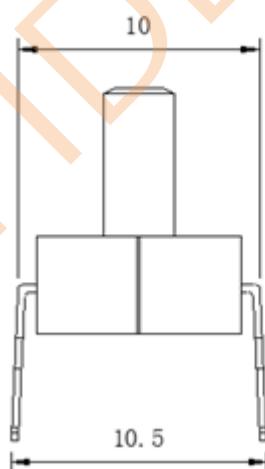
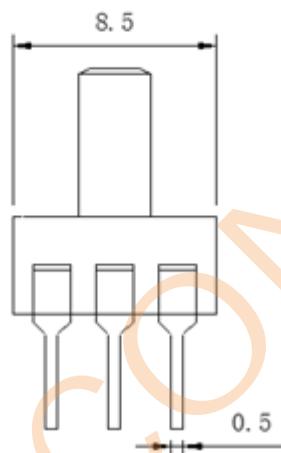
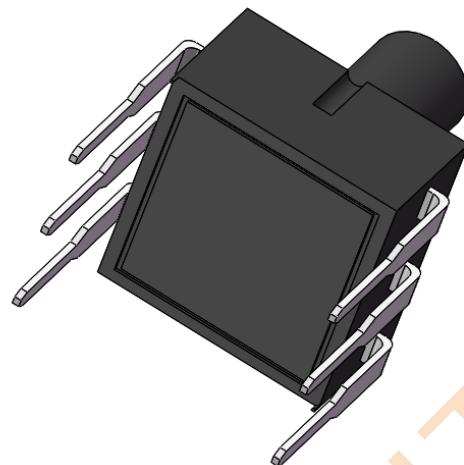
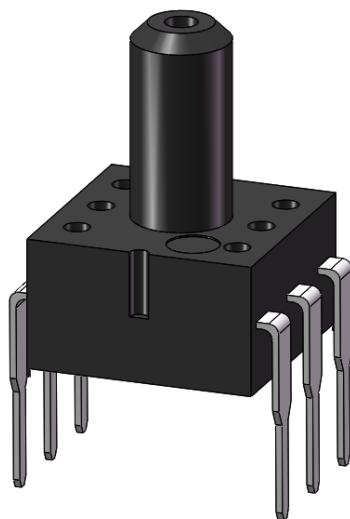
## 8. PRODUCT DIMENSIONS



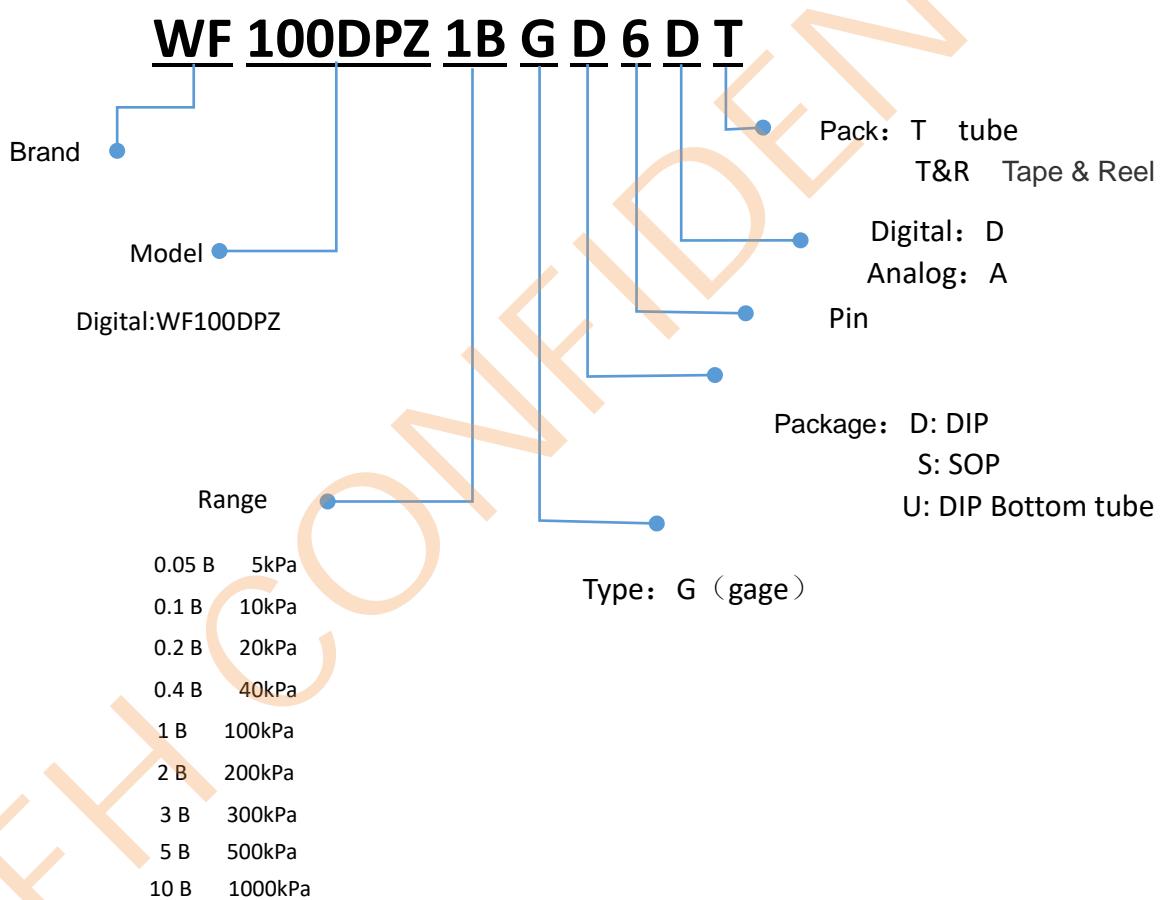
WF100DP SOP6 Top Tube      TOL:  $\pm 0.2\text{mm}$



WF100DP DIP6 Bottom Tube TOL: ±0.2mm

WF100DP DIP6 Top Tube TOL:  $\pm 0.2\text{mm}$

## 9. ORDER INFORMATION



## 10. SOLDERING RECOMMENDATION

The recommended soldering profile is shown in Figure 1 , followed by a description of the profile features in Table 3 .

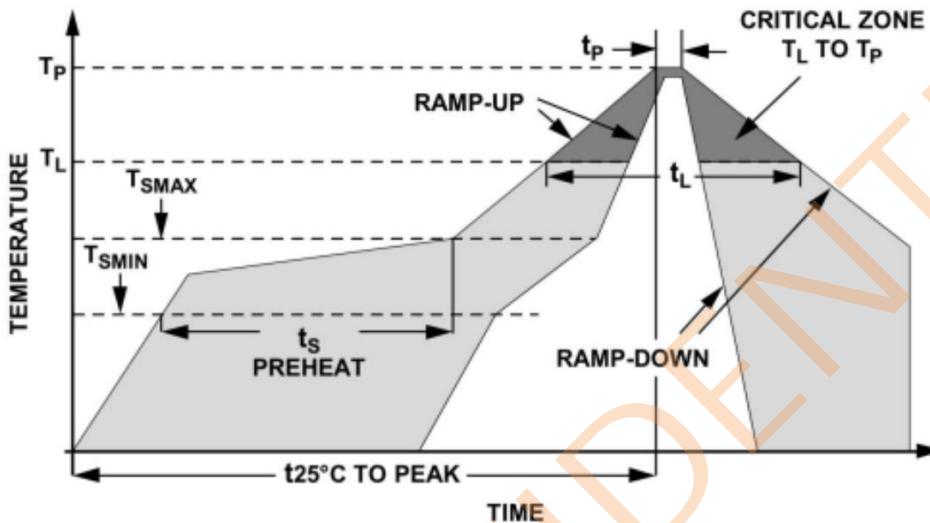


Figure 1 Recommended Soldering Profile

Table 3 Recommended Soldering Profile

Profile Feature	Pb-Free
Average ramp-up rate(TsMax to TP)	3°C/sec max.
Preheat:	
-Temperature Min.(TsMin)	150°C
-Temperature Max.(TxMax)	200°C
-Time.(TsMin to TsMax)(Ts)	60 sec to 180 sec
Time maintained above:	
-Temperature(TL)	217°C
-Time(tL)	60 sec to 150 sec
Peak temperature(TP)	250°C
Time within 5°C of actual peak temperature(TP)2	20 sec to 40 sec
Ramp-down rate	4°C/sec max.
Time 25°C to peak temperature	8 minutes max.